

1 34006/VGG/J104

COPPER SPUTTERING TARGET ASSEMBLY AND METHOD OF MAKING SAME

5 ABSTRACT OF THE DISCLOSURE

Sub A 4 Described is a sputtering target assembly of high purity
copper diffusion bonded to a precipitation hardened aluminum
alloy backing plate via an intermediate layer of a CuCr alloy and
in which the copper contains a micro alloy addition of at least
10 one of Ag, Su, Te, In, Mg, B, Bi, Sb and/or P. Also disclosed
is a method that includes preparation of a master alloy for
addition to high purity copper and fabricating, heat treating and
diffusion bonding processes to produce a sputtering target
assembly with a stable fine-grained target microstructure.

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20 BJE IRV18635.1-*--5/12/99 8:02 am

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